

ADC/DAC board for
Analog Device's BF537 Stamp
board layout by David Pollum
(david.pollum@verizon.net)

Board material:
FR4, 0.062", 1 oz copper
File name/layer stacking:
*.PLC - top silkscreen
*.STC - copper solder mask
*.CMP - top copper
*.SOL - bottom copper
*.STS - bottom solder mask
*.DRD - Excellon NC drill
*.FAB - fabrication drawing

Assembly notes:

- 1) J1, J6, & J7 mount on bottom and mate with connectors on the BF537 Stamp board, so do NOT move them!
- 2) A non-conductive spacer must be used for a #6-32 screw (hole near C4) to secure this board to the Stamp.

Rev-A changes:

changed length from 3.0" to 3.15" to make more room for P1 & P4

Rev-B changes:

- 1) added larger pads (.050" drill) to make it easier to solder wires for +/- 12 volts
- 2) added "1" to mark pin 1 of P1

Drill legend

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◇	3.9624 mm / 156.000 mil
⊠	2.9210 mm / 115.000 mil
□	2.1844 mm / 86.000 mil
⊞	1.7780 mm / 70.000 mil
⚡	1.2700 mm / 50.000 mil
×	1.0160 mm / 40.000 mil
+	0.8128 mm / 32.000 mil
⚡	0.5080 mm / 20.000 mil

